multicomp PRO

RoHS

Compliant



Features

- Faster tripping, 1812 Dimension
- · Surface mount, Solid state
- Holding Current: 0.34A, @ 25°C
- Maximum Voltage: 60V DC
- Operating Temperature: -40°C to +85°C
- Lead-free and Halogen-free

Dimension $A \longrightarrow A$ $B \qquad Marking$

→| |← D

Part Number	Marking	4	4	E	3	(;	D	E
Part Nulliber	Marking	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
MP001612	014	4.37mm	4.73mm	3.07mm	3.41mm	0.5mm	1.1mm	0.3mm	0.15mm

Electrical Specifications

->II E

						Maximum T	ime-to-Trip	Resistance	
Part Number	V мах. (V)	I мах. (A)	Ін (А)	Iт (A)	P₀ (W)	Current (A)	Time (Sec)	Ri _{Min} (Ω)	R1 _{Max.} (Ω)
MP001612	60	100	0.14	0.34	0.8	1.5	0.15	0.65	6

IH: Holding current, maximum current at which the device will not interrupt in 25°C still air.

IT: Tripping current, minimum current at which the device from low resistance to high resistance in 25°C still air.

 $\mathsf{V}_{\mathsf{MAX}}$: Maximum continuous voltage device can withstand without damage at rated current.

IMAX: Maximum fault current device can withstand without damage at rated voltage.

Maximum Time-to-trip: Maximum time to trip at assigned current.

PD: Typical amount of power dissipated from the device when in 25°C still air environment.

RiMin: Minimum resistance of device at 25°C prior to tripping.

R1_{Max}: Maximum resistance of device is measured one hour post reflow.

Thermal Derating Chart-IH (A)

Part Number		Ma	ximum hold	ling current	at assigned	d ambient to	emperature	(A)	
Fart Number	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
MP001612	0.23	0.19	0.17	0.14	0.12	0.1	0.09	0.08	0.06

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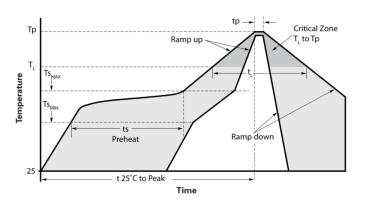
Physical Characteristics

Terminal Pad Materials	Tin-Plated Nickle-copper
Soldering Characteristics	EIA specification RS 186-9E, ANSI/J-STD-002
Moisture Sensitivity	Level 2a, per IPC/JEDEC J-STD 020C

Environmental Specifications

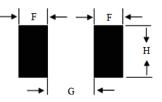
Test Item	Test Conditions	Resistance Change		
Storage life	85°C,1000 hours	±10% typical		
Humidity Aging	85°C/85%RH.100 hours	±5% typical		
Thermal Shock	MIL-STD-202, Method 107G +85°C/-40°C,20 times	-30% typical		
Test Item	Test Conditions	Resistance Change		
Storage Life	85°C,1000 hours	±10% typical		

Solder Reflow Profiles and Pad Layout Dimensions



	Profile Feature	Pb-Free Assembly						
Average Ra	mp-UP Rate(Tsmax to Tp)	3°C/s Max.						
	Temperature Min (Ts min)	150°C						
Preheat	Temperature Max (Ts max)	200°C						
	Time (Tsmin to Ts max)	60sec to 120sec						
Time mainta Temperature Time (t∟)		217°C 60-150 seconds						
Peak/Classi	fication temperature (TP)	260°C						
Time within 5°C of actual peak temperature Time 30 seconds max								
Ramp down	Ramp down rate 3°C / second max							
Time 25°C t	o peak temperature 8 minutes m	ax.						

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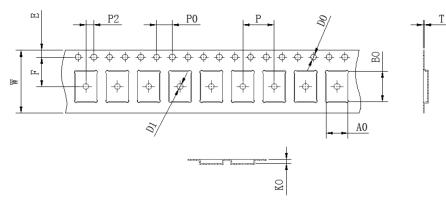
Solder pad layout dimensions

F	G	Н		
1.78mm	3.45mm	3.2mm		



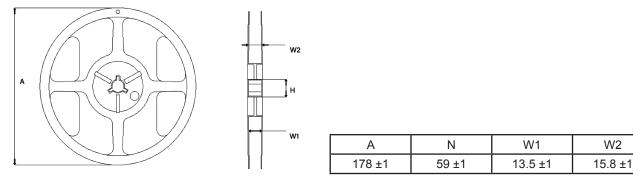
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Packing Information



W	P0	P1	P2	A0	В0	D0	D1	F	E	Т	K0
12 ±0.2	4 ±0.1	8 ±0.1	2 ±0.1	3.58 ±0.1	4.93 ±0.1	1.5 +0.1/-0	1.5 +0.1/-0	5.5 ±0.1	1.75 ±0.1	0.3 ±0.05	0.87 ±0.1 1.15 ±0.1 1.55 ±0.1

Reel Dimensions



Dimensions : Millimetres

Part Number Table

Description	Part Number
PPTC Fuse, 0.34A, 60V DC, 1812	MP001612

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